

HVL355CM

Variable Capacitance Diode for VCO

REJ03G0012-0200Z Rev.2.00 Jun.07.2004

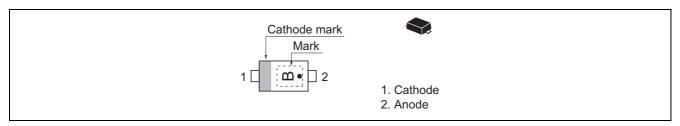
Features

- High capacitance ratio. (n = 2.35 min)
- Low series resistance. (rs = $0.60 \Omega \text{ max}$)
- Thin Extremely small Flat Package (TEFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVL355CM	В	TEFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V _R	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

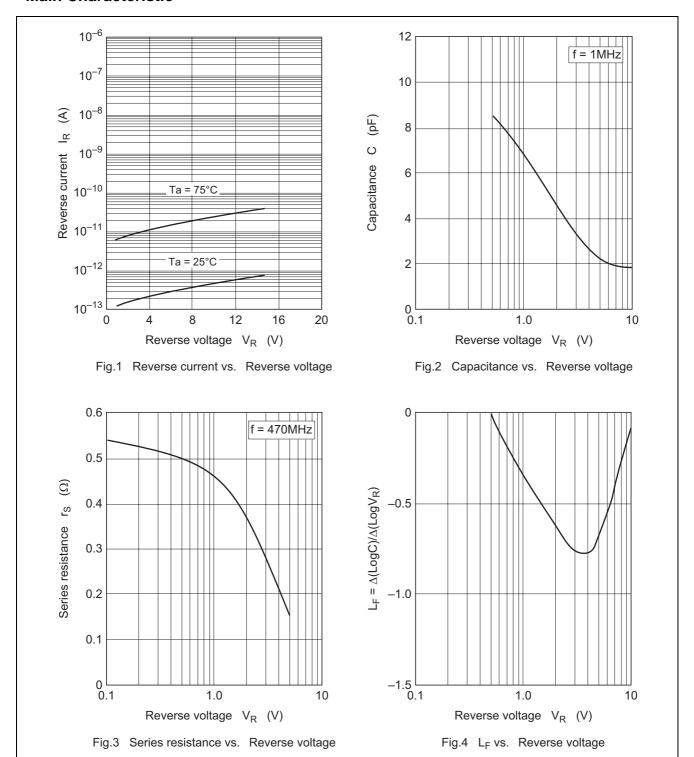
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 15 V
	I _{R2}	_	_	100		V _R = 15 V, Ta = 60°C
Capacitance	C ₁	6.62	_	7.02	pF	$V_R = 1 V, f = 1 MHz$
	C ₄	2.60	_	2.95		$V_R = 4 \text{ V}, f = 1 \text{ MHz}$
Capacitance ratio	n	2.35	_	2.55	_	C ₁ / C ₄
Series resistance	r _S			0.60	Ω	V _R = 1 V, f = 470 MHz

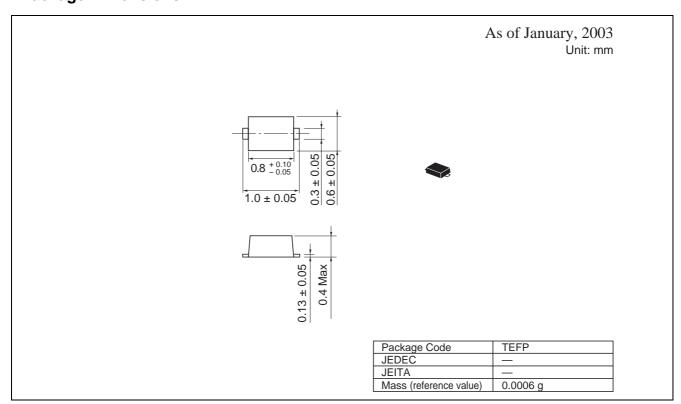
Notes: 1. Please do not use the soldering iron due to avoid high stress to the TEFP package.

^{2.} The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic



Package Dimensions



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